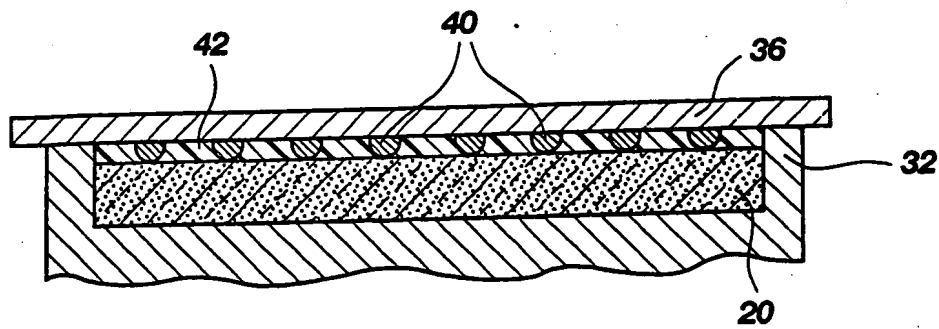
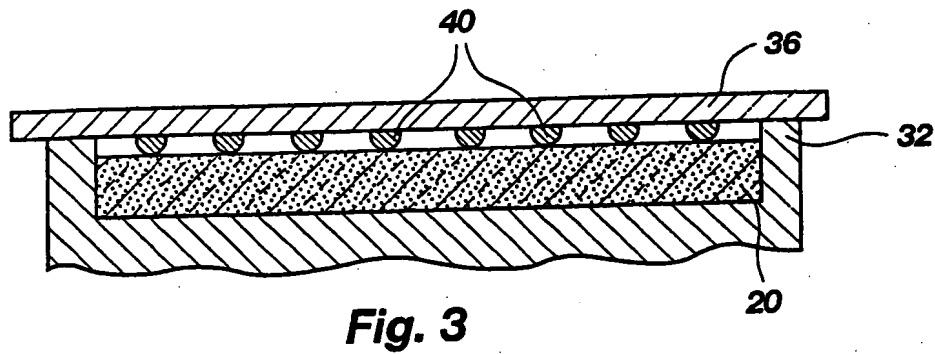
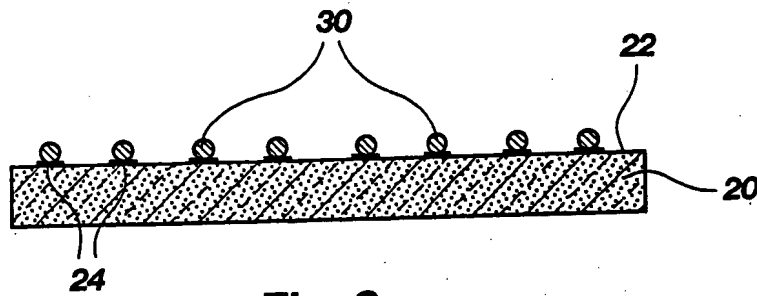
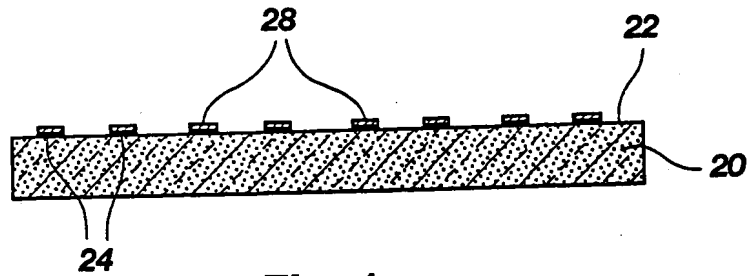


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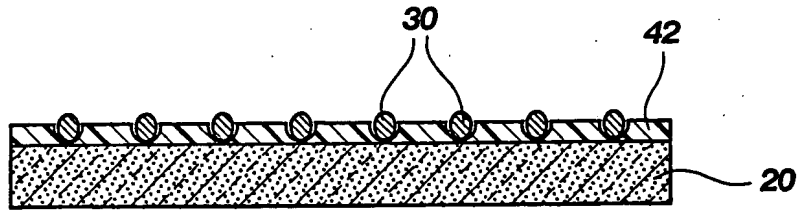


Fig. 5

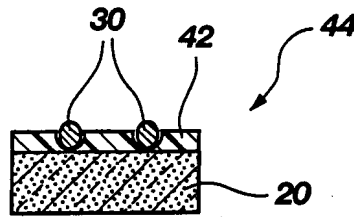


Fig. 6

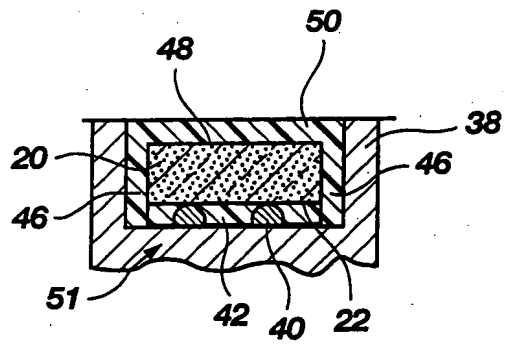


Fig. 7

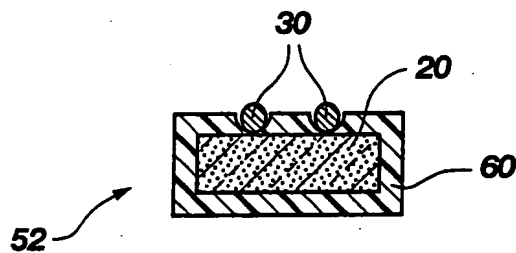


Fig. 8

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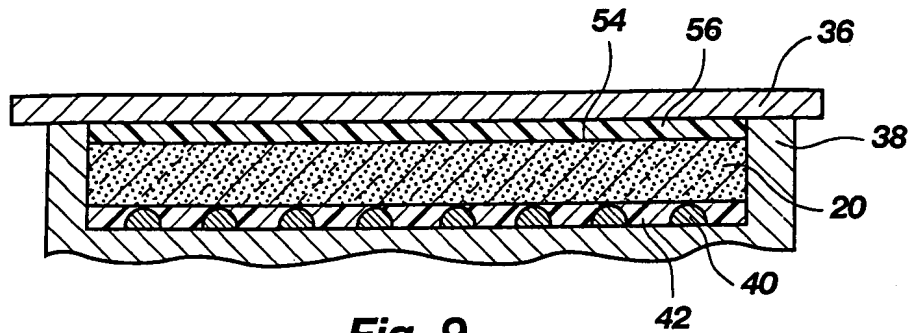


Fig. 9

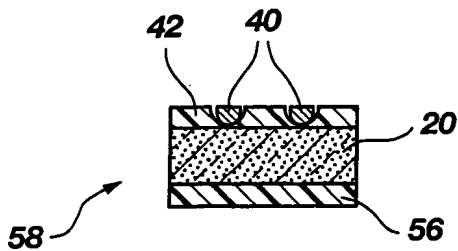


Fig. 10

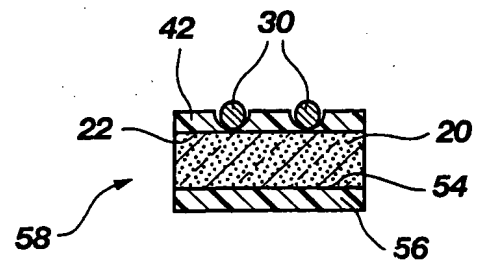


Fig. 11

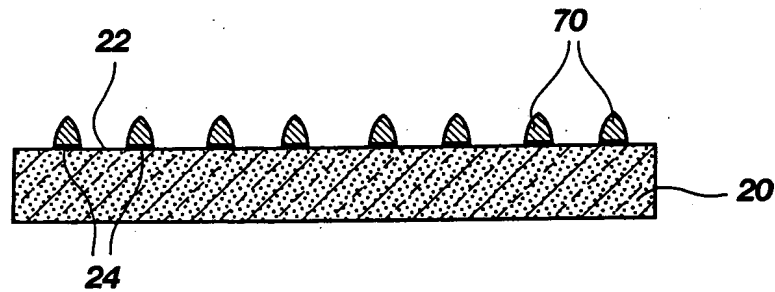


Fig. 12

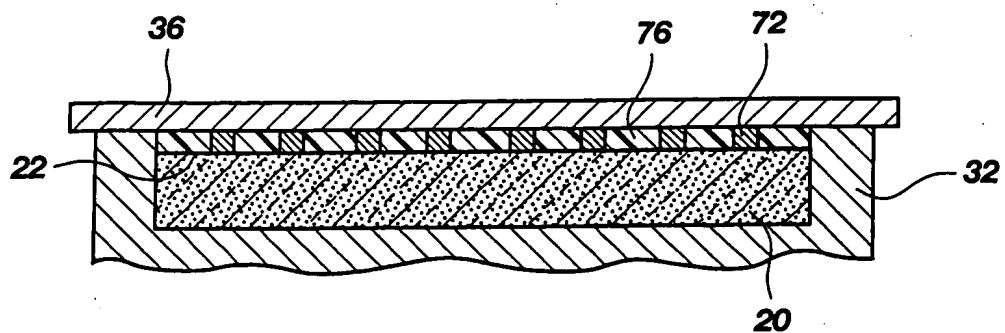


Fig. 13

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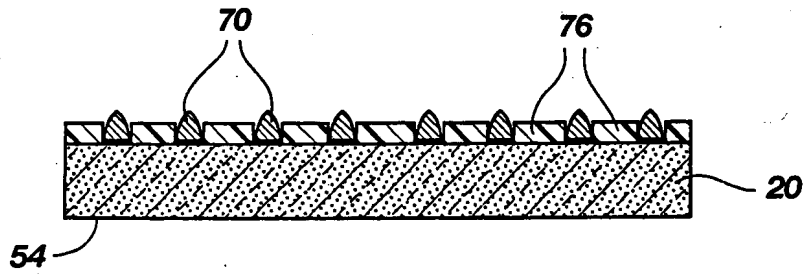


Fig. 14

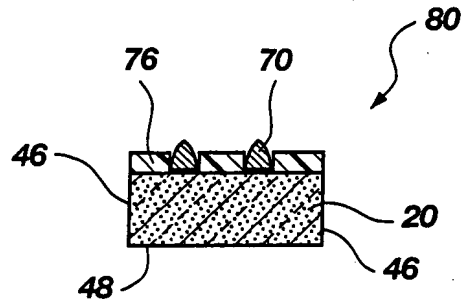


Fig. 15

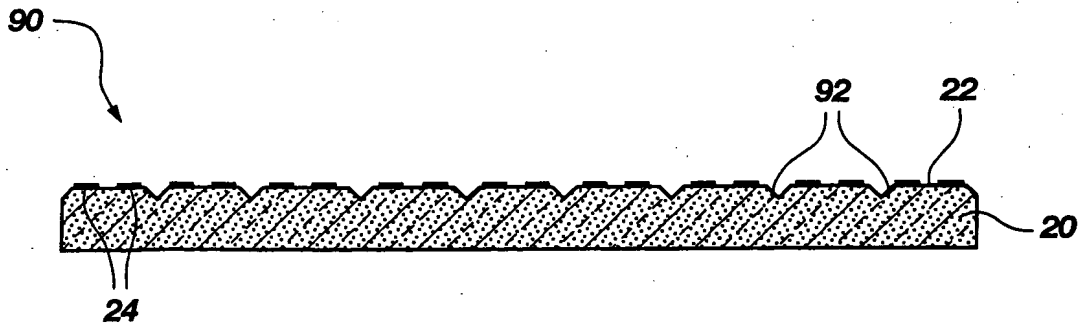


Fig. 16

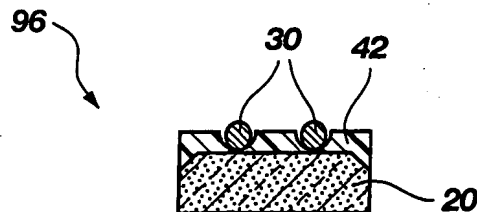


Fig. 17

TITLE: METHOD OF FORMING OVERMOLDED CHIP SCALE
PACKAGE AND RESULTING PRODUCT

Inventor: Warren M. Farnworth

Serial No.: Not Yet Assigned

Docket No.: 3085.4US

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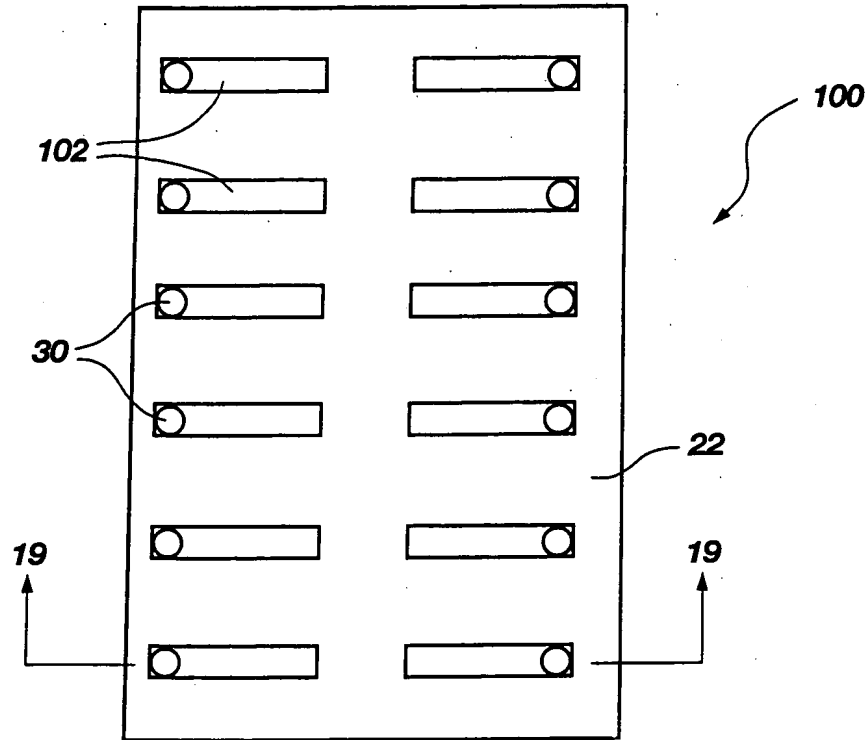


Fig. 18

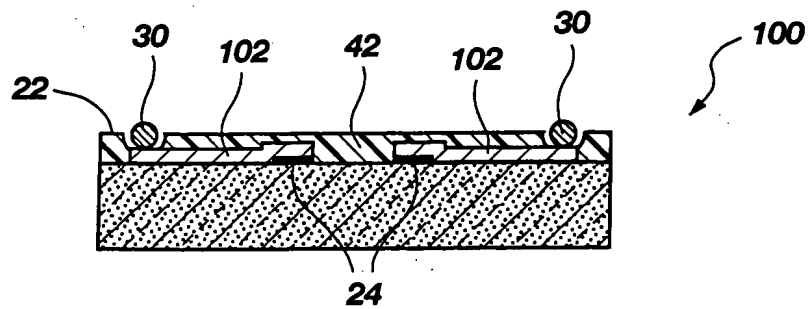


Fig. 19